	Address: Room 605, Building 4, 1970 Science and Technology Park, Minzhi Community, Minzhi Street, Longhua District, Shenzhen 产品规格承认书							
SPECIFICATIONS								
产品名称: DESCRIPTION	1:	Blu	etooth A	ntenna				
产品型号:								
OUR MODEL N	10:		<b>PBX</b> 32	<u>16MP01</u>				
日期:								
DATE:			2020/12/	22				
确认签字,盖章 PLEASE RETU				PECIFICA	TION FOR APP	ROVAL"		
WITH YOUR A	APPROVED	SIGNATU	RES					
Approved	LiuFei	Audit	LiuFei	Making	LiuXiaoMei	]		
Customer	Acknowle	edges Si	.gnature					
	Date							
UNLESS OTHER SPECIF X=± X.X=± ANGLES = ±	X.XX= HOLEDI	$A = \pm$	PENCBANX		市朋伴兴业科	技有限公司		
SCALE: N/A DRAWN BY : Sera	UNIT: mm CHECKED	BY: XD	TECHNOL	OGY Limited AND	PECIFICATIONS ARE THE D SHALL NOT BE REPRO INUFACTURE OR SALE ISION	DUCED OR USED AS		

DOCUMENT NO.

TITLE: CHIP2450-3216 Specification

SPEC REV.

**P1** 

3216

## **PBX3216MP01 Specification**

Operating Temp. : -40℃~+85℃

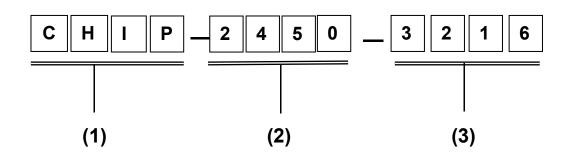
### **1. FEATURES:**

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

## **2. APPLICATIONS:**

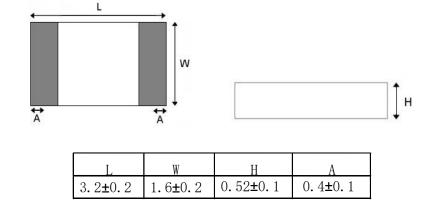
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

## **3. PRODUCT IDENTIFICATION**



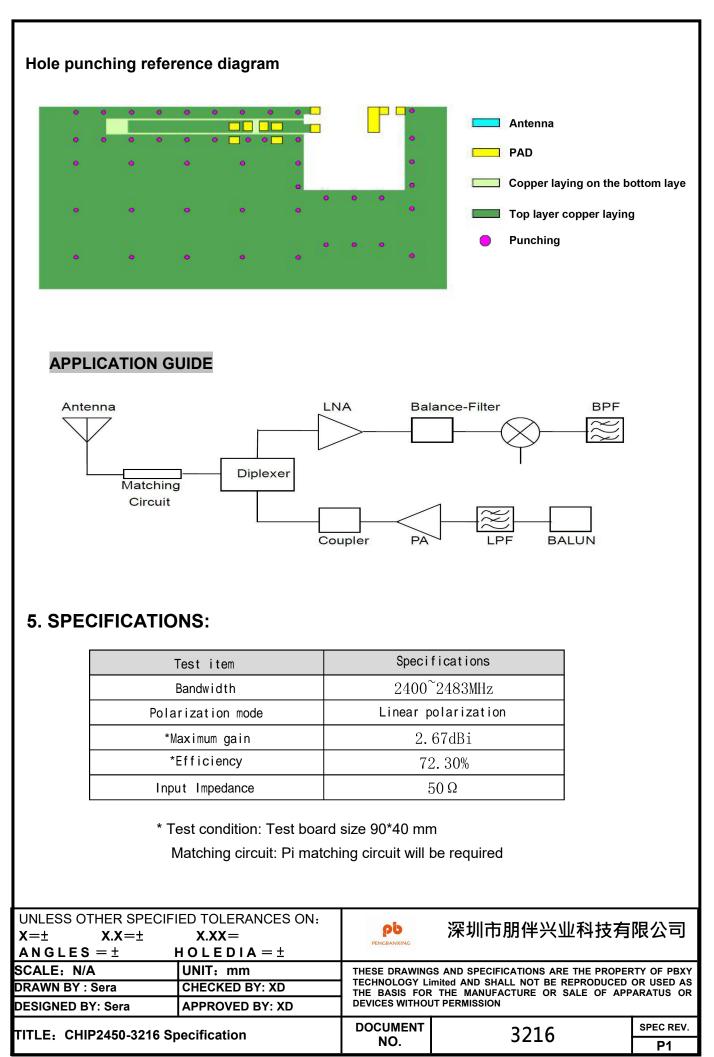
- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 3.2\*1.6

# 4. SHAPE AND DIMENSIONS:



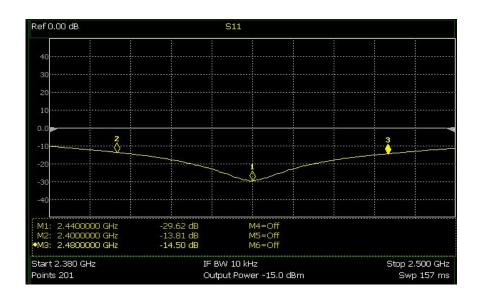
UNLESS OTHER SPECIFIED TOLERANCES ON: $X=\pm$ $X.X=\pm$ $X.XX=$ ANGLES = $\pm$ HOLEDIA = $\pm$		PENGBANXING	深圳市朋伴兴业科技有	限公司
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			5210	P1

Test plate referen Company: mm	ce size:					
			<ul> <li>Antenna</li> <li>PAD</li> <li>Copper laying on the box</li> <li>Top layer copper laying</li> </ul>	tom layer		
	5,3 1 1 5	.5				
UNLESS OTHER SPECIF X=± X.X=± ANGLES = ±	IED TOLERANCES ON: X.XX= H O L E D I A = ±	PENCERANXING	深圳市朋伴兴业科技有	限公司		
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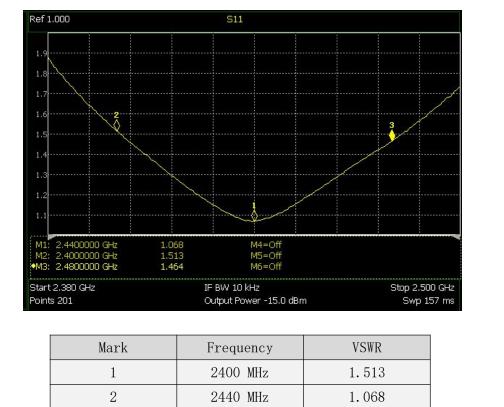


## **Return loss**



#### Standin wave ratio

3



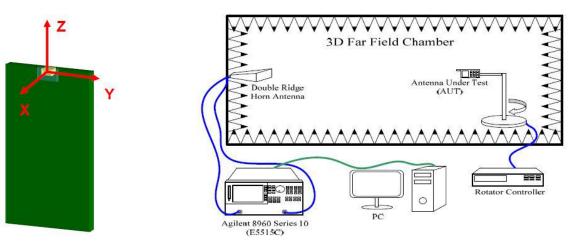
2480 MHz

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DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
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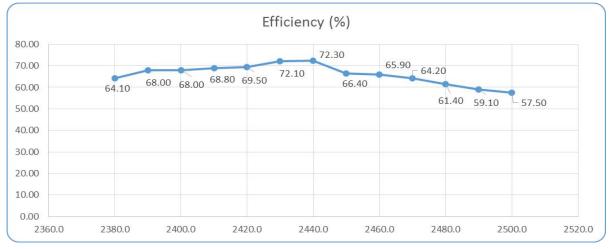
1.464

### **Radiation Pattern**

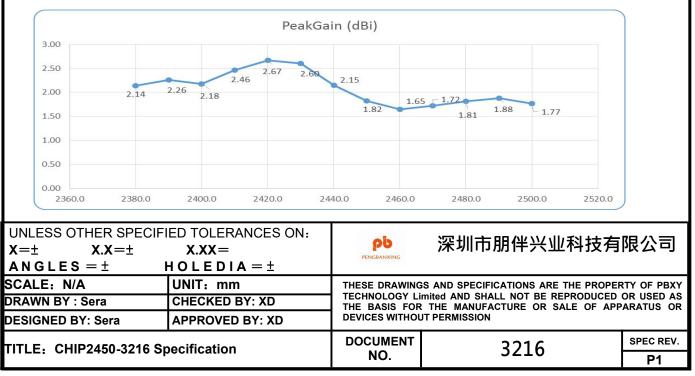
The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.

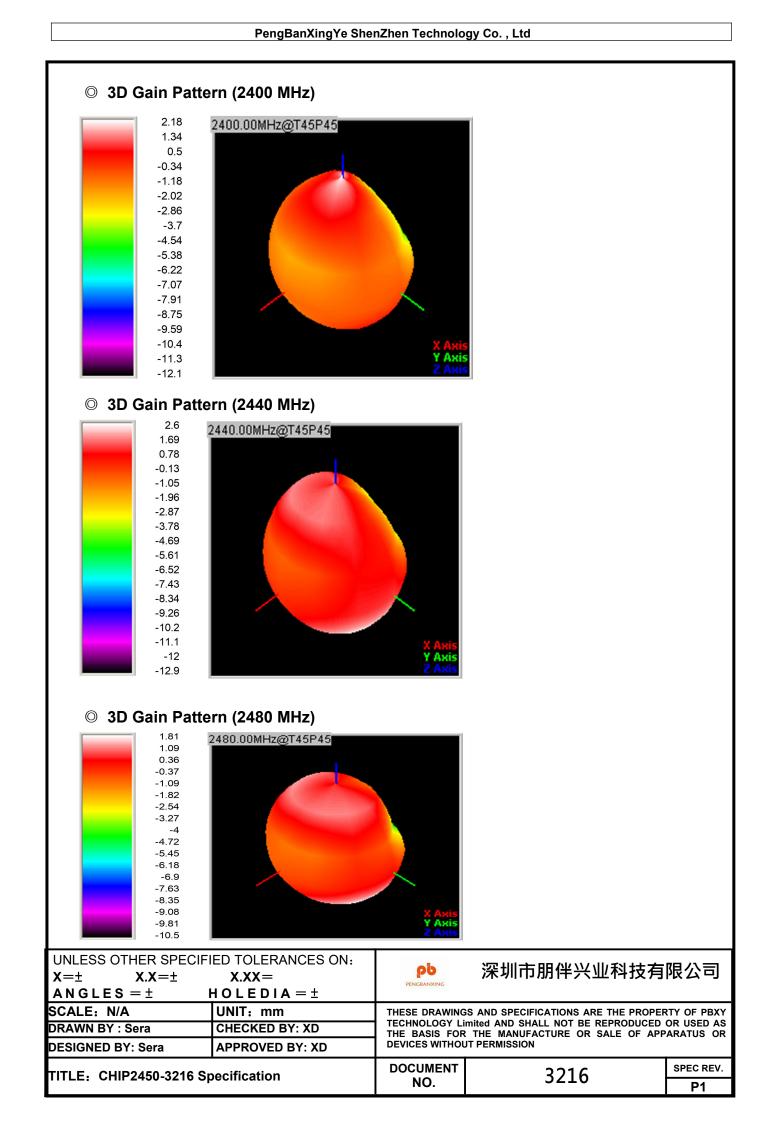


## © Efficiency



### ◎ Maximum gain





# 7. Environmental Characteristics

## (1) Reliability Test

Item	Condition	Specification
Thermal shock	1. $30\pm 3$ minutes at $-40^{\circ} \text{ C}\pm 5^{\circ} \text{ C}$ , 2. Convert to $+105^{\circ} \text{ C}$ (5 minutes) 3. $30\pm 3$ minutes at $+105^{\circ} \text{ C}\pm 5^{\circ} \text{ C}$ , 4. Convert to $-40^{\circ} \text{ C}$ (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85\pm5^{\circ}$ C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5℃ 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm5^\circ$ for $3\pm1$ seconds.	No apparent damage

### (2) Storage Condition

### (a) At warehouse:

The temperature should be within  $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

### (b) On board:

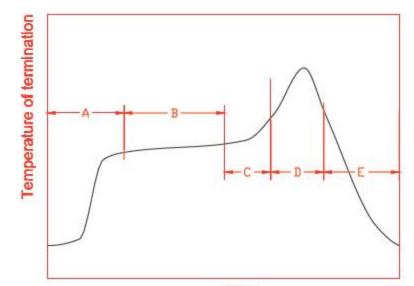
The temperature should be within -40~85°C and humidity should be less than 85% RH.

### (3) Operating Temperature Range

Operating temperature range : -40  $^\circ\!\mathrm{C}$  to +105  $^\circ\!\mathrm{C}$  .

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# 8. Recommended Reflow Soldering



		Time	
A	1 <sup>st</sup> rising temperature	The normal to Preheating temperature	30s to 60s
В	Preheating	140℃ to 160℃	60s to 120s
С	2 <sup>nd</sup> rising temperature	Preheating to 200°C	20s to 40s
	_	if 220°C	50s~60s
		if 230°C	40s~50s
D	Main heating	if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1℃/s ~ 4℃/s
-			

\*reference: J-STD-020C

#### (1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- (a) The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

### (2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

UNLESS OTHER SPECIFIED TOLERANCES ON: $X = \pm$ $X.X = \pm$ $A N G L E S = \pm$ $H O L E D I A = \pm$		PENGBANXING	深圳市朋伴兴业科技有	限公司
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(1) Quantity/Reel: 5000pcs/Reel

